Electronic Patent Application Fee Transmittal

Application Number:	10585461
Filing Date:	
Title of Invention:	Circuit connection material, film-shaped circuit connection material using the same, circuit member connection structure, and manufacturing method thereof
First Named Inventor/Applicant Name:	Jun Taketatsu
Filer:	William Ivan Solomon/Kelli Harris
Attorney Docket Number:	1303.46354X00

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD($)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 4 months with $0 paid	1254	1	1730	1730

Description	Fee Code	Quantity	Amount	Sub-Total in USD($)
Miscellaneous:				
			Total in USD ($)	**1730**